Thermal TGF0200LD 双组份导热凝胶

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Thermal TGF0200LD 是一种具有高导热，低压缩应力和优异可靠性的双组份导热凝胶。其具有良好的弥合公差能力，适用于自动化点胶以及丝网印刷等应用场景。该产品可在常温或高温条件下固化，形成具有弹性的垫片，同时该产品具有较低的密度，能够极大程度的降低物料的重量。

Thermal TGF0200LD is a kind of two-component thermal conductive gel with high thermal conductivity, low compression stress and excellent reliability performance. The material provides good gap filling ability and could be used for automatic dispensing and screen printing. The material can be cured under room or high temperature to form elastic pad after curing. At the same time, this product has a lower density, which can greatly reduce the weight of the material.

Features 特性

- High Thermal Conductivity 高导热
- Low Compression Stress 低应力
- High Reliability 高可靠性
- Low Density 低密度

Applications 产品应用

- Consumer Electronics 消费电子
- Communication Equipment 通讯设备
- Power Supply Controller 电源控制系统
- Smart Wearable Product 智能穿戴产品

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成分	Silicone Filled with Thermal Powder 硅胶&导热粉体		—
Color 颜色	A – Red 红色 B – White 白色 Mix – Red 红色		Visual 目视
Thermal Conductivity 导热系数	2.0	W/m·K	ASTM D5470
Flow Rate 流速（A/B)	70	g/min	30cc EFD, 90Psi
Density 密度	2.0	g/cm^3	ASTM D792
Hardness 硬度（Shore 00）	75	—	ASTM D2240
Cure Time 固化时间	15@150°C 30@85°C	min	—
Temperature Range 耐温范围	-40 - 150	°C	—
Breakdown Voltage 击穿强度	>= 5.0	KV/mm	ASTM D149
Flame Rating 阻燃等级	V-0	—	UL 94
RoHS Compliance 合规性	YES	—	—
Shelf Life 保存期	6	month	25±5°C, ≤50% RH，未启封